

EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
S22 4	5	(barrier and Sn\$1Ag\$1Cu and reflow\$3).clm.	US-PGPUB	OR	ON	2008/01/21 18:39
S22 3	1	(reaction and barrier and Sn\$1Ag\$1Cu and reflow\$3).clm.	US-PGPUB	OR	ON	2008/01/21 18:39
S22 2	2	(reaction and barrier and solder\$3 and reflow\$3).clm.	US-PGPUB	OR	ON	2008/01/21 18:39
S22 1	1	(reaction and barrier and solder\$3 and Sn\$1Ag\$1Cu and reflow\$3).clm.	US-PGPUB	OR	ON	2008/01/21 18:38
S22 0	3	(adhesion and solder\$3 and Sn\$1Ag\$1Cu and reflow\$3).clm.	US-PGPUB	OR	ON	2008/01/21 18:38
S21 9	34	((method or process) and solder\$3 and Sn\$1Ag\$1Cu and reflow\$3).clm.	US-PGPUB	OR	ON	2008/01/21 18:38
S21 8	16	S214 AND Sn\$1Ag\$1Cu with reflow\$3	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/01/21 18:35
S21 7	50	S214 AND Sn\$1Ag\$1Cu	USPAT	OR	ON	2008/01/21 18:32
S21 6	41	(cap or capping) with layer with (sputtering plating evaporation) and S214	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/01/21 18:26
S21 5	19	(cap or capping) with layer with (sputtering plating evaporation) and S214	USPAT	OR	ON	2008/01/21 18:24
S21 4	9478	S210 S211 S212 S213	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/01/21 18:22
S21 3	4137	(438/106).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/01/21 18:21
S21 2	1674	(438/123).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/01/21 18:21

EAST Search History

S21 1	1831	(438/613).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/01/21 18:21
S21 0	3079	(438/612).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/01/21 18:21
S20 9	327	(438/611).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/01/21 18:21
S20 8	2	"6,143,588".pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/01/21 17:53
S20 7	1	S206 and copper	USPAT; DERWENT	OR	ON	2008/01/21 17:53
S20 6	2	(US-7081404-\$.did. or (WO-2004075265-\$.did.	USPAT; DERWENT	OR	ON	2008/01/21 17:53
S20 5	1	tin near1 "95" near antimony	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/01/21 17:53
S20 4	1737	tin near2 bismuth near antimony	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/01/21 17:53
S20 3	1	tin near2 bismuth near antimonium	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/01/21 17:53
S20 2	104	tin near2 bismuth near eutectic	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/01/21 17:53

EAST Search History

S20 1	128	tin near2 silver near eutectic	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/01/21 17:53
S20 0	2	"20050224966".PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/01/21 17:53
S19 9	2	"7081404".PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/01/21 17:53
S19 8	35	("4185318" "4527259" "4554643" "4868632" "5357134" "5408115" "5467308" "5763308" "5768192" "5859459" "5877523" "5923978" "6348387" "6424002" "6563151" "6624465").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/01/21 17:53
S19 7	65	S196 not S195	USPAT	OR	ON	2008/01/21 17:53
S19 6	96	solder with wettable with (sputtering plating evaporation)	USPAT	OR	ON	2008/01/21 17:53
S19 5	31	solder with wettable with (sputtering plating evaporation) and "438"/\$.ccls.	USPAT	OR	ON	2008/01/21 17:53
S19 4	2	(sn tin) with plating with low with cost and "438"/\$.ccls.	USPAT	OR	ON	2008/01/21 17:53
S19 3	1	(sn) with plating with low with cost and "438"/\$.ccls.	USPAT	OR	ON	2008/01/21 17:53
S19 2	42	(gold au) with plating with cost and "438"/\$.ccls.	USPAT	OR	ON	2008/01/21 17:53
S19 1	27	metal with deposit\$5 with (sputtering plating evaporation) with cost and "438"/\$.ccls.	USPAT	OR	ON	2008/01/21 17:53
S19 0	1414039	metal deposit\$5 with (sputtering plating evaporation) with cost and "438"/\$.ccls.	USPAT	OR	ON	2008/01/21 17:53
S18 9	2	metal near2 layer with deposit\$5 with (sputtering plating evaporation) with cost and "438"/\$.ccls.	USPAT	OR	ON	2008/01/21 17:53
S18 8	0	(ball c4 bump flip solder near2 ball) same metal near2 layer with deposit\$5 with (sputtering plating evaporation) with cost and "438"/\$.ccls.	USPAT	OR	ON	2008/01/21 17:53

EAST Search History

S18 7	5	(ball c4 bump flip solder near2 ball) same (cap or capping) with layer with (sputtering plating evaporation) and "438"/\$.ccls.	USPAT	OR	ON	2008/01/21 17:53
S18 6	350	(cap or capping) with layer with (sputtering plating evaporation) and "438"/\$.ccls.	USPAT	OR	ON	2008/01/21 17:53
S18 5	5	(cap or capping) with layer with (sputtering plating evaporation) and 257/737.ccls.	USPAT	OR	ON	2008/01/21 17:53
S18 4	860	(cap or capping) with layer with (sputtering plating evaporation)	USPAT	OR	ON	2008/01/21 17:53
S18 3	1	"5,234,149".pn. and (cap capping)	USPAT	OR	ON	2008/01/21 17:53
S18 2	1	"5532612".pn. and anneal\$5 with minutes	USPAT	OR	ON	2008/01/21 17:53
S18 1	1	"5532612".pn. and anneal\$5	USPAT	OR	ON	2008/01/21 17:53
S18 0	31	(bump solder near2 ball) with anneal\$5 and anneal\$5 with (min minutes hour second)	USPAT	OR	ON	2008/01/21 17:53
S17 9	106	(bump solder near2 ball) with anneal\$5	USPAT	OR	ON	2008/01/21 17:53
S17 8	11	(bump solder near2 ball) with anneal\$5 with (min minutes hour second)	USPAT	OR	ON	2008/01/21 17:53
S17 7	2	(bump solder near2 ball) with anneal\$5 with minutes	USPAT	OR	ON	2008/01/21 17:53
S17 6	4	wettable with layer with (copper cu) and pure near2 (tin sn) with (bump ball c4)	USPAT	OR	ON	2008/01/21 17:53
S17 5	200	wettable with layer with (copper cu)	USPAT	OR	ON	2008/01/21 17:53
S17 4	2	tin with bump same cu with wett\$6	USPAT	OR	ON	2008/01/21 17:53
S17 3	0	tin with bump with cu with wettable	USPAT	OR	ON	2008/01/21 17:53
S17 2	1	"5,234,149".pn.	USPAT	OR	ON	2008/01/21 17:53
S17 1	210	wettable with (layer film) with (gold au)	USPAT	OR	ON	2008/01/21 17:53
S17 0	2	final with wettable with (layer film) with (gold au)	USPAT	OR	ON	2008/01/21 17:53
S16 9	58	bump with plating with seed with layer	USPAT	OR	ON	2008/01/21 17:53
S16 8	64	bump same (au gold) with wetting	USPAT	OR	ON	2008/01/21 17:53
S16 7	5	au with bump with plating with seed	USPAT	OR	ON	2008/01/21 17:53

EAST Search History

S16 6	6	gold with bump with plating with seed	USPAT	OR	ON	2008/01/21 17:53
S16 5	23182	gold with bump wit plating with seed	USPAT	OR	ON	2008/01/21 17:53
S16 4	12	barrier with wetting with layer with au	USPAT	OR	ON	2008/01/21 17:53
S16 3	113	barrier with au with bump	USPAT	OR	ON	2008/01/21 17:53
S16 2	1	barrier with au with wettab\$5 with bump	USPAT	OR	ON	2008/01/21 17:53
S16 1	35	S159 and 257/737.ccls.	USPAT	OR	ON	2008/01/21 17:53
S16 0	71	S159 and 257/737.ccls.	US-PGPUB; USPAT; USOCR	OR	ON	2008/01/21 17:53
S15 9	788	(BLM UBM) with (ti tin ta tan zr znn v ni)	US-PGPUB; USPAT; USOCR	OR	ON	2008/01/21 17:53
S15 8	10	(BLM UBM) with adhesion with thickness	US-PGPUB; USPAT; USOCR	OR	ON	2008/01/21 17:53
S15 7	2	("20020137325" "6492197").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/01/21 17:53
S15 6	47	"438"/\$.ccls. and (Pb lead) near2 free and (BLM UBM) and sputtering	USPAT	OR	ON	2008/01/21 17:53
S15 5	30	S154 and (Pb lead) near2 free and (BLM UBM)	USPAT	OR	ON	2008/01/21 17:53
S15 4	2330	(438/614).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/01/21 17:53
S15 3	2	S152 and lead near2 free	USPAT	OR	ON	2008/01/21 17:53
S15 2	8	("4835593" "5162257" "5244143" "5767010" "5775569" "5937320" "6003757" "6056191").PN.	USPAT	OR	ON	2008/01/21 17:53
S15 1	2	"20050224966".pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/01/21 17:53
S15 0	16	("4835593" "5162257" "5244143" "5767010" "5775569" "5937320" "6003757" "6056191").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/01/21 17:53

EAST Search History

S14 9	177	andujar.xp.	USPAT	OR	ON	2008/01/21 17:53
S14 8	184	(armando with rodriguez).xp.	USPAT	OR	ON	2008/01/21 17:53
S14 7	359	(armando with rodriguez).xa.	USPAT	OR	ON	2008/01/21 17:53
S14 6	309	((flores or ruiz) with delma).xa.	USPAT	OR	ON	2008/01/21 17:53
S14 5	31	epoxy near1 resin with commonly with used with (reliability moldability, moisture absorbing resistance adhesion)	USPAT	OR	ON	2008/01/21 17:53
S14 4	29	S143 and "257"\$.ccls.	USPAT	OR	ON	2008/01/21 17:53
S14 3	88	encapsulat\$3 with epoxy with prefer\$5	US-PGPUB; USPAT; USOCR	OR	ON	2008/01/21 17:53
S14 2	2664	S141 and "257"\$.ccls.	USPAT	OR	ON	2008/01/21 17:53
S14 1	11490	encapsulat\$3 with epoxy	US-PGPUB; USPAT; USOCR	OR	ON	2008/01/21 17:53
S14 0	37	S139 and "257"\$.ccls.	USPAT	OR	ON	2008/01/21 17:53
S13 9	103	encapsulat\$3 with epoxy with cost	US-PGPUB; USPAT; USOCR	OR	ON	2008/01/21 17:53
S13 8	34	S135 and "257"\$.ccls.	USPAT	OR	ON	2008/01/21 17:53
S13 7	59	S135 and "257"\$.ccls.	US-PGPUB; USPAT; USOCR	OR	ON	2008/01/21 17:53
S13 6	0	S135 and 257/797.ccls.	US-PGPUB; USPAT; USOCR	OR	ON	2008/01/21 17:53
S13 5	134	molding with epoxy with cost	US-PGPUB; USPAT; USOCR	OR	ON	2008/01/21 17:53
S13 4	1	"6114752".pn.	US-PGPUB; USPAT; USOCR	OR	ON	2008/01/21 17:53
S13 3	34	"6114752"	US-PGPUB; USPAT; USOCR	OR	ON	2008/01/21 17:53
S13 2	12	("4884124" "5223740" "5233222" "5264730" "5327008" "5521428" "5550402" "5661338" "5683944" "5723897" "5963782" "6049120").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/01/21 17:53

EAST Search History

S13 1	4	("5140404" "5491362" "6114752" "6191490").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/01/21 17:53
S13 0	35	("4258381" "4857989" "5214307").PN. OR ("6114752"). URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/01/21 17:53
S12 9	8	("5140404" "5491362" "6114752" "6191490").PN. OR ("6440779"). URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/01/21 17:53
S12 8	35	("4258381" "4857989" "5214307").PN. OR ("6114752"). URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/01/21 17:53
S12 7	12	("4532222" "5986209" "6114752" "6 424031" "6504238" "6638790").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/01/21 17:53
S12 6	171	S124 and S125	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/01/21 17:53
S12 5	10264	(257/666-677).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/01/21 17:53
S12 4	2258	(chip IC die) with pad with ring	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/01/21 17:53
S12 3	204	(chip IC die) with pad with rim	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/01/21 17:53
S12 2	5630	pad with rim	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/01/21 17:53
S12 1	11	S120 not S115	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/01/21 17:53

EAST Search History

S12 0	21	S119 and pad with rim	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/01/21 17:53
S11 9	10264	(257/666-677).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/01/21 17:53
S11 8	309036	"257"/(666-677).ccls. and pad with rim	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/01/21 17:53
S11 7	309036	"257"/(666-677).ccls. and pad with rim	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/01/21 17:53
S11 6	309036	"257"/(666-677).ccls. and pad with rim	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/01/21 17:53
S11 5	10	S114 and pad with rim	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/01/21 17:53
S11 4	2706	(257/676).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/01/21 17:53
S11 3	1	"6373127".pn. and tape	US-PGPUB; USPAT; USOCR	OR	ON	2008/01/21 17:53

EAST Search History

S11 2	71	("20030073265" "3838984" "4530152" "4707724" "4756080" "4812896" "5041902" "5157480" "5172213" "5172214" "5200362" "5200809" "5214845" "5216278" "5221642" "5258094" "5273938" "5277972" "5278446" "5279029" "5332864" "5336931" "5343076" "5391439" "5406124" "5424576" "5435057" "5521429" "5604376" "5608267" "5639990" "5640047" "5641997" "5646831" "5650663" "5683806" "5696666" "5701034" "5710064" "5736432" "5776798" "5783861" "5835988" "5859471" "5866939" "5877043" "5894108" "5977613" "5977630" "5981314" "6001671" "6018189" "6025640" "6130115" "6130473" "6143981" "6198171" "6225146" "6229200" "6242281" "6281568" "6437429" "6448633" "6483178" "6545332" "6580161" "6611047" "6700189" "6861734").PN. OR ("7042068"). URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/01/21 17:53
S11 1	135	("5172214" "5521429").PN. OR ("5977613").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/01/21 17:53
S11 0	84	("3838984" "4530152" "4707724" "4756080" "4812896" "5041902" "5157480" "5172213" "5172214" "5200362" "5200809" "5214845" "5216278" "5221642" "5258094" "5273938" "5277972" "5278446" "5279029" "5332864" "5336931" "5343076" "5406124" "5424576" "5435057" "5474958" "5521429" "5604376" "5608267" "5639990" "5640047" "5641997" "5646831" "5650663" "5683806" "5696666" "5701034" "5710064" "5776798" "5783861" "5835988" "5859471" "5866939" "5877043" "5894108" "5977613" "5977630" "5981314" "5981314" "6001671" "6025640" "6130115" "6130473" "6143981" "6198171" "6225146" "6229200" "6242281" "6281568").PN. OR ("6455356").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/01/21 17:53
S10 9	65	("5270491" "5529959" "5811799" "5898218" "6191359" "6208020" "6303978" "6355502").PN. OR ("6476469").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/01/21 17:53

EAST Search History

S10 8	25	("20010030355" "20010042904" "20020041011" "20020079561" "20020121684" "20020153597" "20030001244" "20030006492" "20030042581" "20030073265" "4283839" "5466966" "6025640" "6075284" "6078098" "6081029" "6166430" "6211462" "6229200" "6448633" "6455356" "6462424" "6476469" "6521987" "6700186"). PN. OR ("6979886").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/01/21 17:53
S10 7	11	("0127711" "6504238" "6828661" "6 900524" "6979886").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/01/21 17:53
S10 6	2	"6,143,588".pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/09/28 19:01
S10 5	1	S104 and copper	USPAT; DERWENT	OR	ON	2007/09/28 17:20
S10 4	2	(US-7081404-\$).did. or (WO-2004075265-\$).did.	USPAT; DERWENT	OR	ON	2007/09/28 17:20
S10 3	1	tin near1 "95" near antimony	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/09/28 16:32
S10 2	1712	tin near2 bismuth near antimony	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/09/28 16:27
S10 1	1	tin near2 bismuth near antimonium	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/09/28 16:25
S10 0	99	tin near2 bismuth near eutectic	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/09/28 16:24

EAST Search History

S99	121	tin near2 silver near eutectic	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/09/28 16:20
S98	2	"20050224966".PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/09/28 16:17
S97	2	"7081404".PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/09/28 16:09
S96	35	("4185318" "4527259" "4554643" "4868632" "5357134" "5408115" "5467308" "5763308" "5768192" "5859459" "5877523" "5923978" "6348387" "6424002" "6563151" "6624465").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/10/30 11:41
S95	62	S94 not S93	USPAT	OR	ON	2006/10/28 18:29
S94	88	solder with wettable with (sputtering plating evaporation)	USPAT	OR	ON	2006/10/28 18:29
S93	26	solder with wettable with (sputtering plating evaporation) and "438"/\$.ccls.	USPAT	OR	ON	2006/10/28 18:29
S92	2	(sn tin) with plating with low with cost and "438"/\$.ccls.	USPAT	OR	ON	2006/10/28 18:24
S91	1	(sn) with plating with low with cost and "438"/\$.ccls.	USPAT	OR	ON	2006/10/28 18:24
S90	40	(gold au) with plating with cost and "438"/\$.ccls.	USPAT	OR	ON	2006/10/28 18:24
S89	22	metal with deposit\$5 with (sputtering plating evaporation) with cost and "438"/\$.ccls.	USPAT	OR	ON	2006/10/28 18:22
S88	1344965	metal deposit\$5 with (sputtering plating evaporation) with cost and "438"/\$.ccls.	USPAT	OR	ON	2006/10/28 18:21
S87	1	metal near2 layer with deposit\$5 with (sputtering plating evaporation) with cost and "438"/\$.ccls.	USPAT	OR	ON	2006/10/28 18:21
S86	0	(ball c4 bump flip solder near2 ball) same metal near2 layer with deposit\$5 with (sputtering plating evaporation) with cost and "438"/\$.ccls.	USPAT	OR	ON	2006/10/28 18:20

EAST Search History

S85	4	(ball c4 bump flip solder near2 ball) same (cap or capping) with layer with (sputtering plating evaporation) and "438"/\$.ccls.	USPAT	OR	ON	2006/10/28 18:19
S84	290	(cap or capping) with layer with (sputtering plating evaporation) and "438"/\$.ccls.	USPAT	OR	ON	2006/10/28 18:18
S83	5	(cap or capping) with layer with (sputtering plating evaporation) and 257/737.ccls.	USPAT	OR	ON	2006/10/28 18:16
S82	737	(cap or capping) with layer with (sputtering plating evaporation)	USPAT	OR	ON	2006/10/28 18:16
S81	1	"5,234,149".pn. and (cap capping)	USPAT	OR	ON	2006/10/28 18:15
S80	1	"5532612".pn. and anneal\$5 with minutes	USPAT	OR	ON	2006/10/28 18:13
S79	1	"5532612".pn. and anneal\$5	USPAT	OR	ON	2006/10/28 18:04
S75	2	(bump solder near2 ball) with anneal\$5 with minutes	USPAT	OR	ON	2006/10/28 18:03
S78	29	(bump solder near2 ball) with anneal\$5 and anneal\$5 with (min minutes hour second)	USPAT	OR	ON	2006/10/28 17:45
S77	94	(bump solder near2 ball) with anneal\$5	USPAT	OR	ON	2006/10/28 17:44
S76	10	(bump solder near2 ball) with anneal\$5 with (min minutes hour second)	USPAT	OR	ON	2006/10/28 17:44
S74	4	wettable with layer with (copper cu) and pure near2 (tin sn) with (bump ball c4)	USPAT	OR	ON	2006/10/28 17:40
S73	191	wettable with layer with (copper cu)	USPAT	OR	ON	2006/10/28 17:06
S72	2	tin with bump same cu with wett\$6	USPAT	OR	ON	2006/10/28 17:04
S71	0	tin with bump with cu with wettable	USPAT	OR	ON	2006/10/28 17:04
S70	1	"5,234,149".pn.	USPAT	OR	ON	2006/10/28 17:03
S69	180	wettable with (layer film) with (gold au)	USPAT	OR	ON	2006/10/28 16:09
S68	2	final with wettable with (layer film) with (gold au)	USPAT	OR	ON	2006/10/28 16:04
S67	52	bump with plating with seed with layer	USPAT	OR	ON	2006/10/28 16:03
S66	54	bump same (au gold) with wetting	USPAT	OR	ON	2006/10/28 15:58
S65	4	au with bump with plating with seed	USPAT	OR	ON	2006/10/28 15:52
S64	6	gold with bump with plating with seed	USPAT	OR	ON	2006/10/28 15:50
S63	21062	gold with bump wit plating with seed	USPAT	OR	ON	2006/10/28 15:47
S62	12	barrier with wetting with layer with au	USPAT	OR	ON	2006/10/28 15:46
S61	103	barrier with au with bump	USPAT	OR	ON	2006/10/28 15:45

EAST Search History

S60	1	barrier with au with wettab\$5 with bump	USPAT	OR	ON	2006/10/28 15:43
S59	31	S57 and 257/737.ccls.	USPAT	OR	ON	2006/10/28 15:41
S58	58	S57 and 257/737.ccls.	US-PGPUB; USPAT; USOCR	OR	ON	2006/10/28 15:27
S57	651	(BLM UBM) with (ti tin ta tan zr znn v ni)	US-PGPUB; USPAT; USOCR	OR	ON	2006/10/28 15:26
S56	8	(BLM UBM) with adhesion with thickness	US-PGPUB; USPAT; USOCR	OR	ON	2006/10/28 15:25
S55	2	("20020137325" "6492197").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/10/28 15:06
S54	29	"438"/\$.ccls. and (Pb lead) near2 free and (BLM UBM) and sputtering	USPAT	OR	ON	2006/10/28 13:59
S53	24	S52 and (Pb lead) near2 free and (BLM UBM)	USPAT	OR	ON	2006/10/28 13:58
S52	2223	(438/614).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/10/28 13:54
S51	2	S50 and lead near2 free	USPAT	OR	ON	2006/10/28 13:54
S50	8	("4835593" "5162257" "5244143" "5767010" "5775569" "5937320" "6003757" "6056191").PN.	USPAT	OR	ON	2006/10/28 13:53
S48	16	("4835593" "5162257" "5244143" "5767010" "5775569" "5937320" "6003757" "6056191").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/10/28 13:52
S49	2	"20050224966".pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/10/28 13:23
S47	42	andujar.xp.	USPAT	OR	ON	2006/10/24 16:14
S46	61	(armando with rodriguez).xp.	USPAT	OR	ON	2006/10/24 16:11
S45	359	(armando with rodriguez).xa.	USPAT	OR	ON	2006/10/24 16:11
S44	283	((flores or ruiz) with delma).xa.	USPAT	OR	ON	2006/10/24 16:10
S43	29	epoxy near1 resin with commonly with used with (reliability moldability, moisture absorbing resistance adhesion)	USPAT	OR	ON	2006/10/24 16:10
S39	25	S38 and "257"\$.ccls.	USPAT	OR	ON	2006/10/24 15:11

EAST Search History

S38	77	encapsulat\$3 with epoxy with prefer\$5	US-PGPUB; USPAT; USOCR	OR	ON	2006/10/24 15:09
S37	2386	S36 and "257"\$.ccls.	USPAT	OR	ON	2006/10/24 15:09
S36	10021	encapsulat\$3 with epoxy	US-PGPUB; USPAT; USOCR	OR	ON	2006/10/24 15:08
S35	31	S34 and "257"\$.ccls.	USPAT	OR	ON	2006/10/24 15:08
S34	90	encapsulat\$3 with epoxy with cost	US-PGPUB; USPAT; USOCR	OR	ON	2006/10/24 15:08
S33	32	S30 and "257"\$.ccls.	USPAT	OR	ON	2006/10/24 15:06
S30	122	molding with epoxy with cost	US-PGPUB; USPAT; USOCR	OR	ON	2006/10/24 15:06
S32	48	S30 and "257"\$.ccls.	US-PGPUB; USPAT; USOCR	OR	ON	2006/10/24 15:01
S31	0	S30 and 257/797.ccls.	US-PGPUB; USPAT; USOCR	OR	ON	2006/10/24 15:01
S29	1	"6114752".pn.	US-PGPUB; USPAT; USOCR	OR	ON	2006/10/24 15:00
S28	24	"6114752"	US-PGPUB; USPAT; USOCR	OR	ON	2006/10/24 14:53
S27	12	("4884124" "5223740" "5233222" "5264730" "5327008" "5521428" "5550402" "5661338" "5683944" "5723897" "5963782" "6049120").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/10/24 14:53
S26	4	("5140404" "5491362" "6114752" "6191490").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/10/24 14:37
S25	25	("4258381" "4857989" "5214307").PN. OR ("6114752"). URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/10/24 10:46
S24	8	("5140404" "5491362" "6114752" "6191490").PN. OR ("6440779"). URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/10/24 10:45
S23	25	("4258381" "4857989" "5214307").PN. OR ("6114752"). URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/10/24 10:43
S22	12	("4532222" "5986209" "6114752" "6 424031" "6504238" "6638790").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/10/24 10:42

EAST Search History

S21	148	S19 and S20	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/10/24 10:04
S20	9559	(257/666-677).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/10/24 10:04
S19	1986	(chip IC die) with pad with ring	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/10/24 10:04
S18	182	(chip IC die) with pad with rim	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/10/24 10:04
S17	5273	pad with rim	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/10/23 15:05
S16	11	S15 not S10	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/10/23 15:04
S15	18	S14 and pad with rim	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/10/23 15:04
S14	9553	(257/666-677).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/10/23 15:04
S13	282813	"257"/(666-677).ccls. and pad with rim	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/10/23 15:04

EAST Search History

S12	282813	"257"/(666-677).ccls. and pad with rim	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/10/23 15:03
S11	282813	"257"/(666-677).ccls. and pad with rim	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/10/23 15:02
S10	7	S8 and pad with rim	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/10/23 15:02
S8	2477	(257/676).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/10/23 15:00
S7	1	"6373127".pn. and tape	US-PGPUB; USPAT; USOCR	OR	ON	2006/10/23 14:59
S6	69	("20030073265" "3838984" "4530152" "4707724" "4756080" "4812896" "5041902" "5157480" "5172213" "5172214" "5200362" "5200809" "5214845" "5216278" "5221642" "5258094" "5273938" "5277972" "5278446" "5279029" "5332864" "5336931" "5343076" "5391439" "5406124" "5424576" "5435057" "5521429" "5604376" "5608267" "5639990" "5640047" "5641997" "5646831" "5650663" "5683806" "5696666" "5701034" "5710064" "5736432" "5776798" "5783861" "5835988" "5859471" "5866939" "5877043" "5894108" "5977613" "5977630" "5981314" "6001671" "6018189" "6025640" "6130115" "6130473" "6143981" "6198171" "6225146" "6229200" "6242281" "6281568" "6437429" "6448633" "6483178" "6545332" "6580161" "6611047" "6700189" "6861734").PN. OR ("7042068"). URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/10/23 14:42
S5	116	("5172214" "5521429").PN. OR ("5977613").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/10/23 14:03

EAST Search History

S4	77	("3838984" "4530152" "4707724" "4756080" "4812896" "5041902" "5157480" "5172213" "5172214" "5200362" "5200809" "5214845" "5216278" "5221642" "5258094" "5273938" "5277972" "5278446" "5279029" "5332864" "5336931" "5343076" "5406124" "5424576" "5435057" "5474958" "5521429" "5604376" "5608267" "5639990" "5640047" "5641997" "5646831" "5650663" "5683806" "5696666" "5701034" "5710064" "5776798" "5783861" "5835988" "5859471" "5866939" "5877043" "5894108" "5977613" "5977615" "5977630" "5981314" "6001671" "6025640" "6130115" "6130473" "6143981" "6198171" "6225146" "6229200" "6242281" "6281568").PN. OR ("6455356").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/10/23 13:55
S3	45	("5270491" "5529959" "5811799" "5898218" "6191359" "6208020" "6303978" "6355502").PN. OR ("6476469").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/10/23 13:51
S2	25	("20010030355" "20010042904" "20020041011" "20020079561" "20020121684" "20020153597" "20030001244" "20030006492" "20030042581" "20030073265" "4283839" "5466966" "6025640" "6075284" "6078098" "6081029" "6166430" "6211462" "6229200" "6448633" "6455356" "6462424" "6476469" "6521987" "6700186"). PN. OR ("6979886").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/10/23 13:49
S1	11	("0127711" "6504238" "6828661" "6 900524" "6979886").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/10/23 13:48